

Esec 2100 FC hS



Driving Innovation

Flip chip in high volume production means more cost pressure, both in investment and in operating cost. Flip chip bonding on low cost substrates like metal leadframes and thin laminate strips is seeing fast growth.

Besì as a renowned leader in providing FC bonders for trouble free high quality mass production has integrated flip chip capability into the latest generation of the 2100 family - an aggressive approach to driving down the cost of flip chip technology.

Future Proof Equipment



Lowest Cost of Ownership

- 8 μ m placement accuracy at high speed
- Full process control - highest yield
- Quickest device changeover
- Reduced operating cost - 2100 Platform Synergies

FULL PROCESS CONTROL



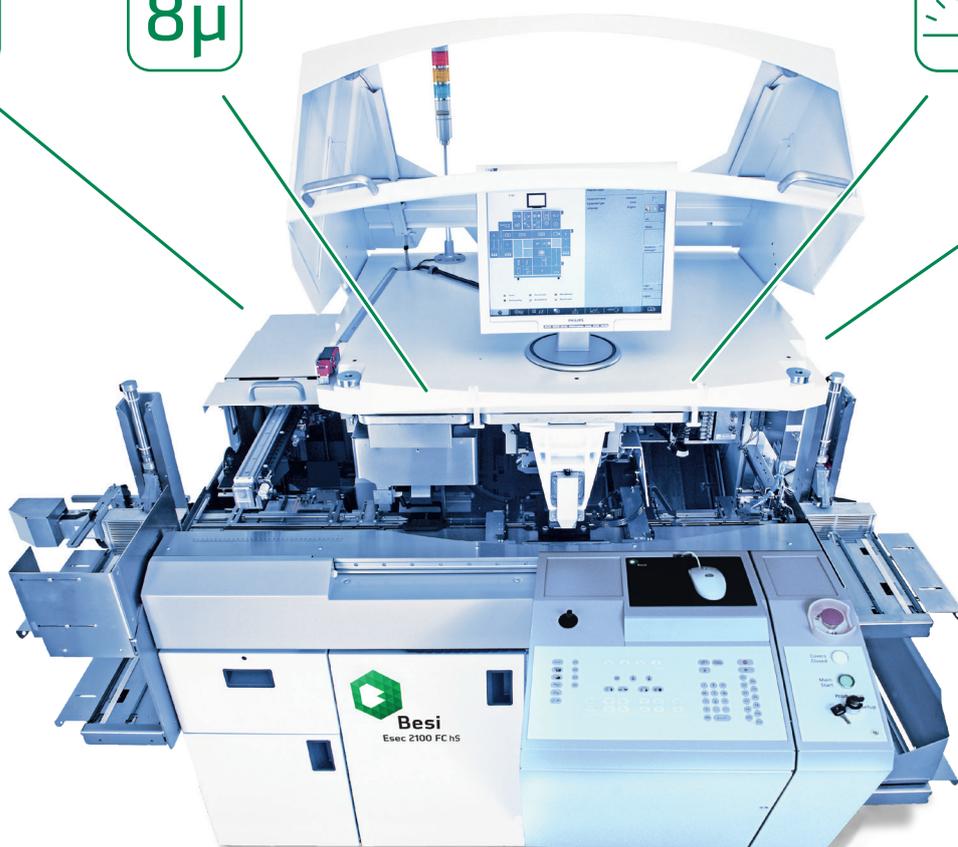
ACCURACY



HIGHEST OUTPUT

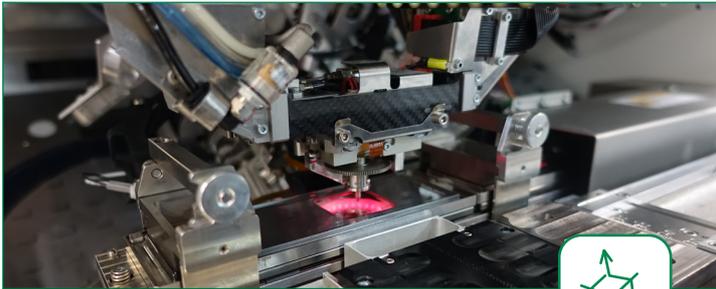


EASE OF USE



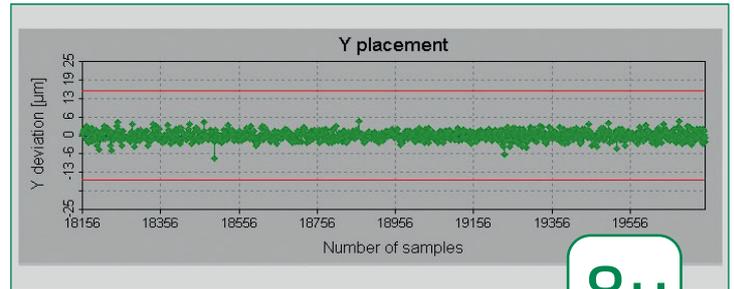


www.besi.com - sales@besi.com



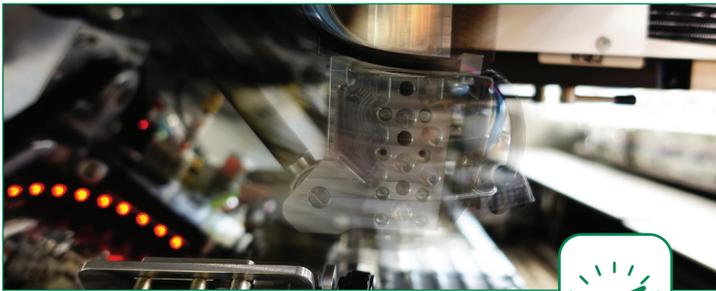
Full Process Control

- Post Bond Inspection (PBI) without uph loss
- Automatic flux imprint monitoring
- Real-time touch down check at flux and bond to avoid non-wet issues and cold solder joints
- Flux coverage inspection with patented fluxer concept
- Programmable pick / bond force down to 0.2 N



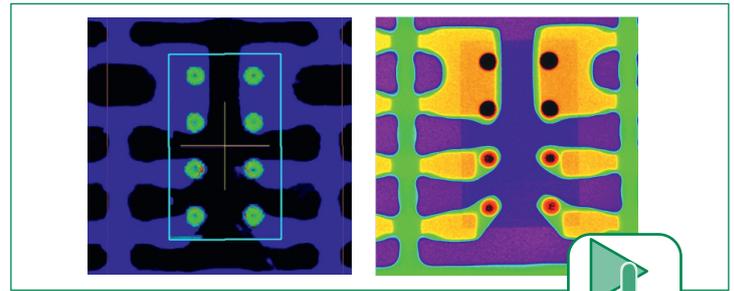
Accuracy

- Improved Pick and Place Z-axis guides and bearings
- Placement Auto Correction
- 2nd generation vision system with improved image quality
- Enhanced thermal drift compensation



Highest Output

- Independent movement of chip and cameras
- Unique P&P concept – no time wasted for motion settling
- Optimized for strip based products
- Simultaneous bump alignment and dip fluxing
- Patented Slide Fluxer concept with integrated up-looking camera



Ease of Use

- Full recipe transfer from machine to machine
- PSEUDO X-RAY™ - First Die Right
- Quick and easy product conversion without tools
- Automatic Flip Head alignment

Feature	Esec 2100 FC hS	Datacon 8800 FC QUANTUM ^{advanced}	Datacon 8800 CHAMEO ^{advanced}
Local Accuracy	8 µm @ 3s (HAM)	5 µm @ 3s	3 µm @ 3s
Global Accuracy	-	-	5 µm @ 3s
Max. Strips, Boats, Panels Width	4" (up to 6.3" opt.)	8"	13"
Die Size	0.2 × 0.2 - 20 × 20 mm	0.3 × 0.3 - 20 × 20 mm	0.3 × 0.3 - 30 × 30 mm
Multi Chip (single pass)	-	-	✓
UPH (with dip fluxing)	up to 16,000	up to 10,000	up to 7,000
Heated Tool/Substrate	-	-	opt. (constant)
Pre-Heat Station	-	-	opt.
Inline Dispensing	opt.	-	-